Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.016”**

**B**

**E**

**.016”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .004 x .004”**

**Backside Potential: COLLECTOR**

**APPROVED BY: DK DIE SIZE .016” X .016” DATE: 10/5/21**

**MFG: MOTOROLA THICKNESS .010” P/N: 2N2920**

**DG 10.1.2**

#### Rev B, 7/1